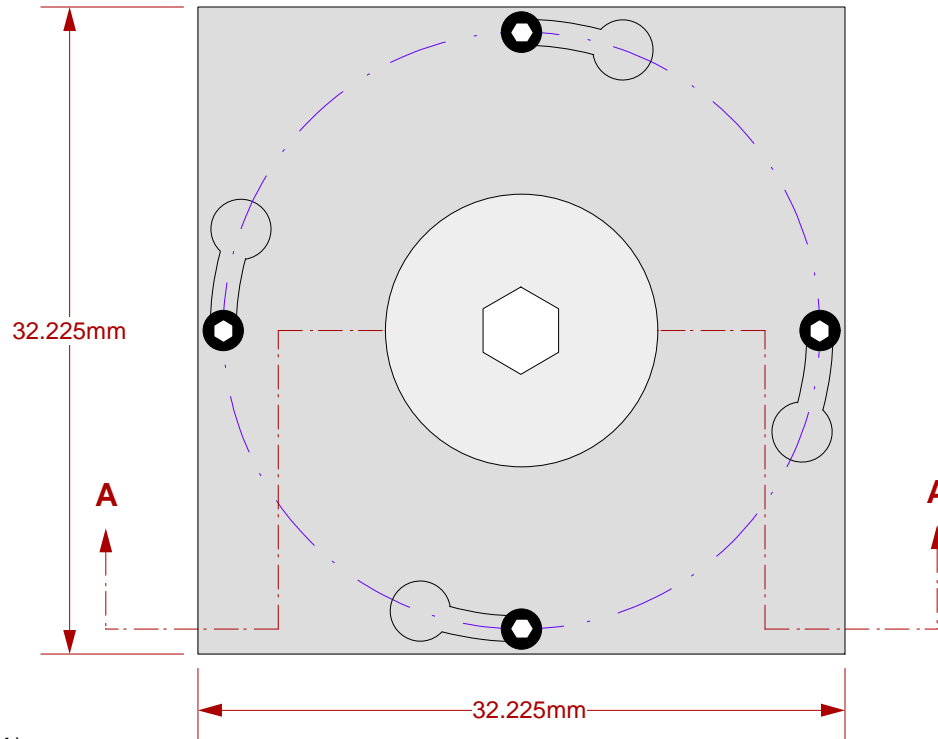
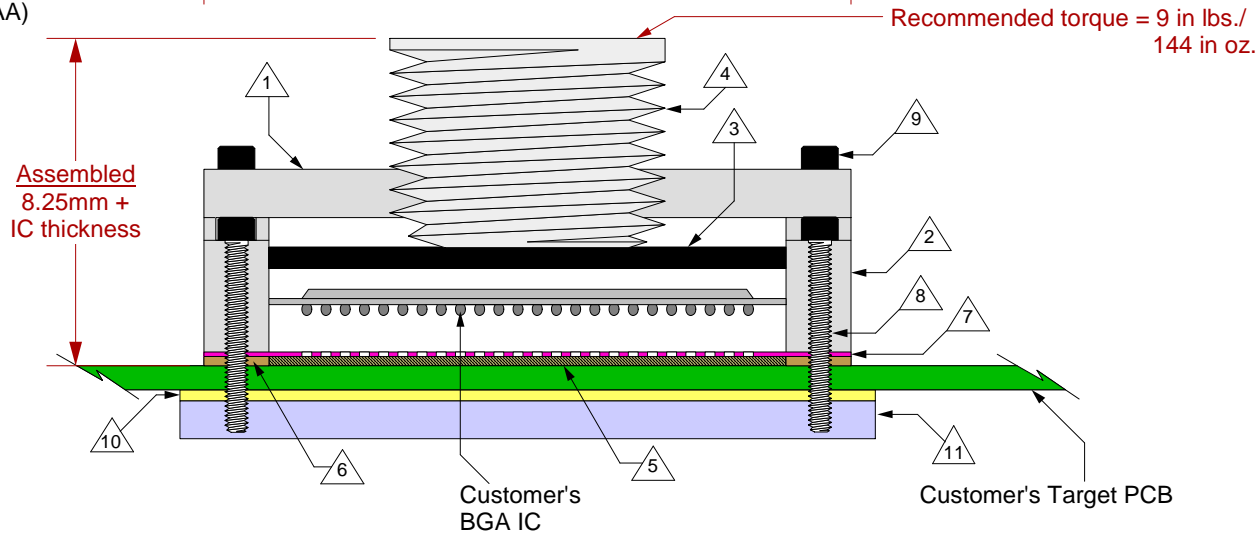


Top View



Side View
(Section AA)



GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Fillister head, Alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, 1.59mm thick.
- △ 11 Backing Plate: Anodized Aluminum 6.35mm thick.

SG-BGA-6181 Drawing

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11351 Rupp Dr. Suite 400, Burnsville MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

Drawing: H. Hansen

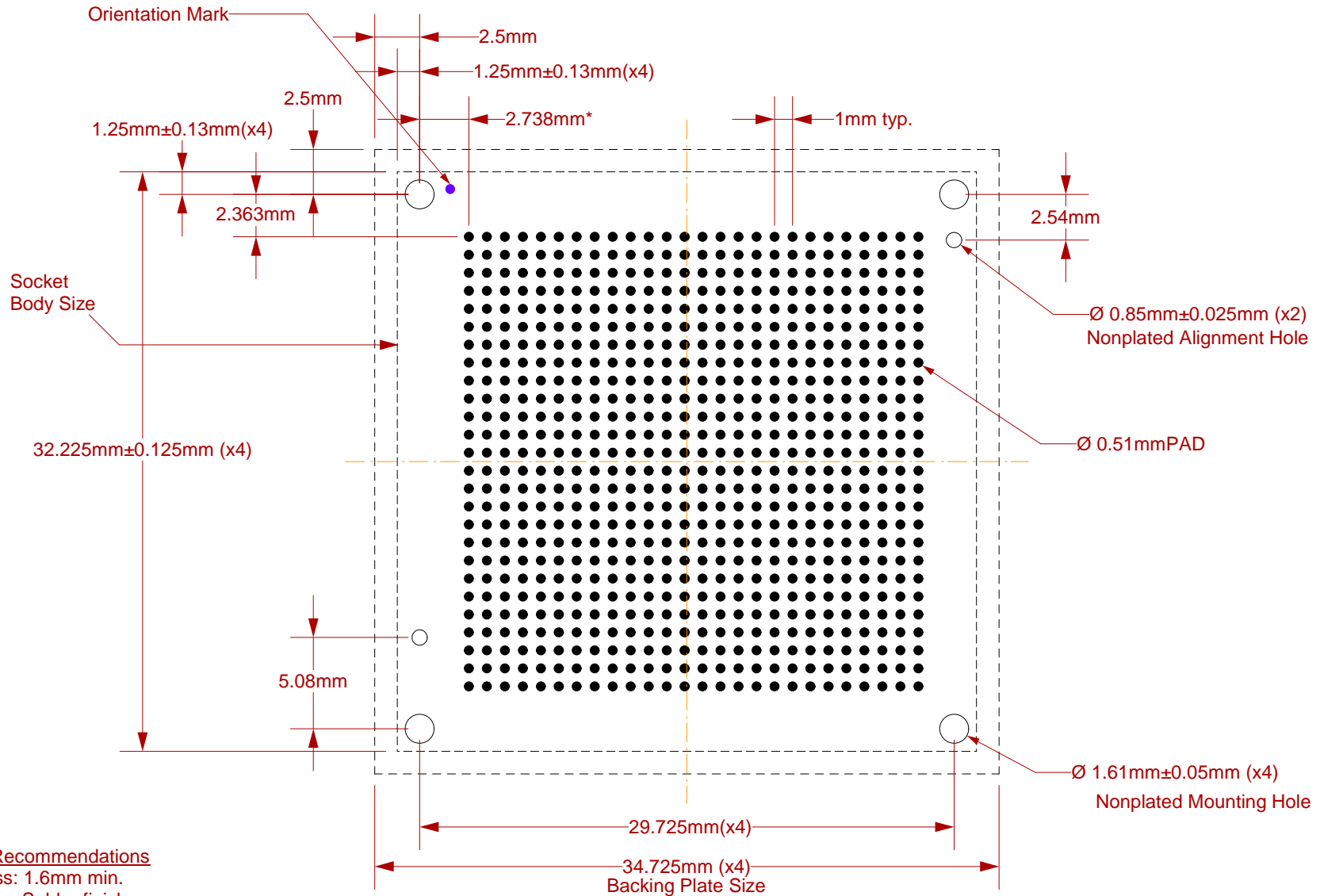
Date: 8/22/06

File: SG-BGA-6181 Dwg

Modified: 5/19/09

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



Target PCB Recommendations

Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SG-BGA-6181 Drawing

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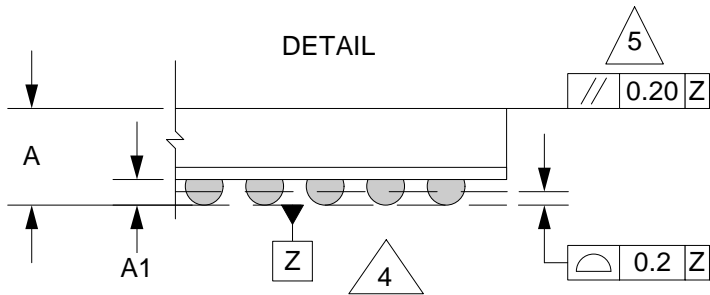
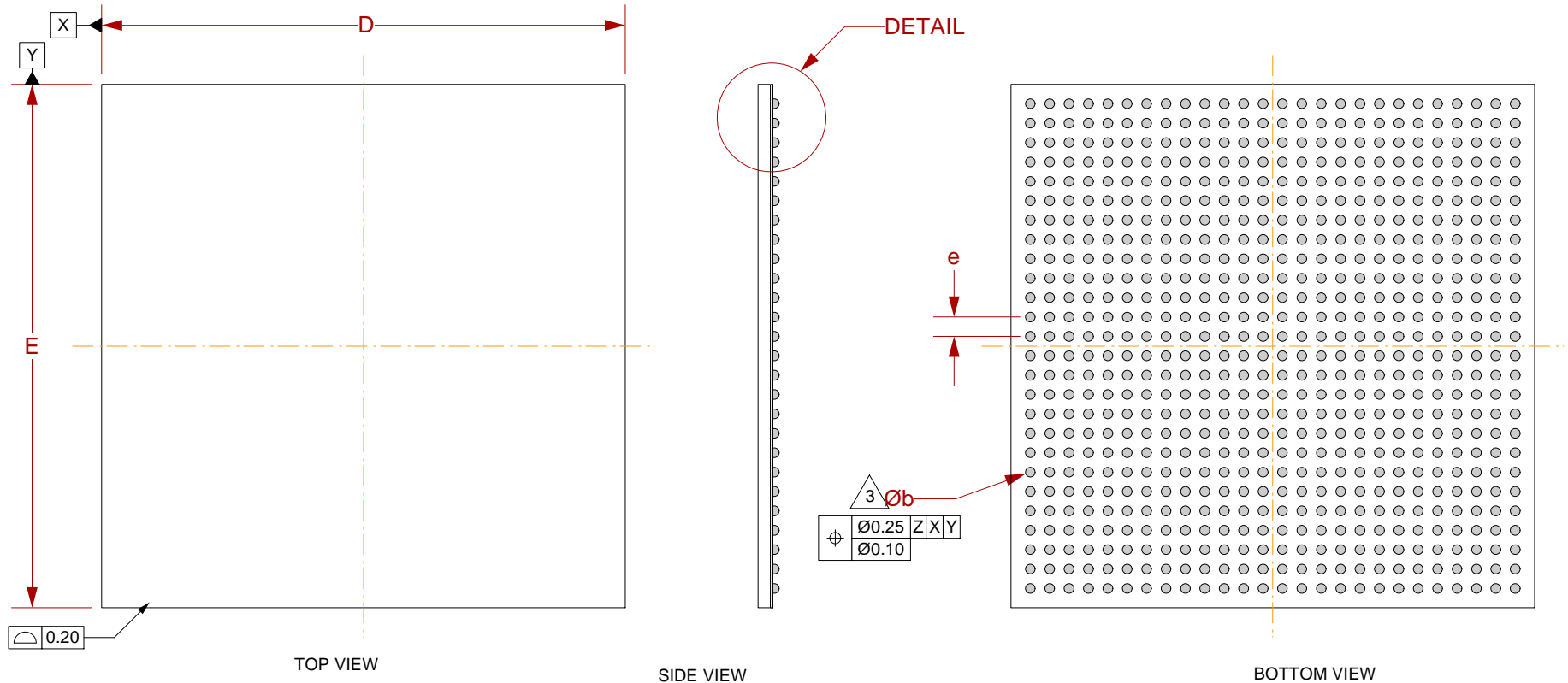
Rev: B

Drawing: H. Hansen

Date: 8/22/06

File: SG-BGA-6181 Dwg

Modified: 5/19/09



1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- △3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - △4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - △5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.6
A1	0.3	0.6
b		0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.0 BSC	

Array 26x26

SG-BGA-6181 Drawing

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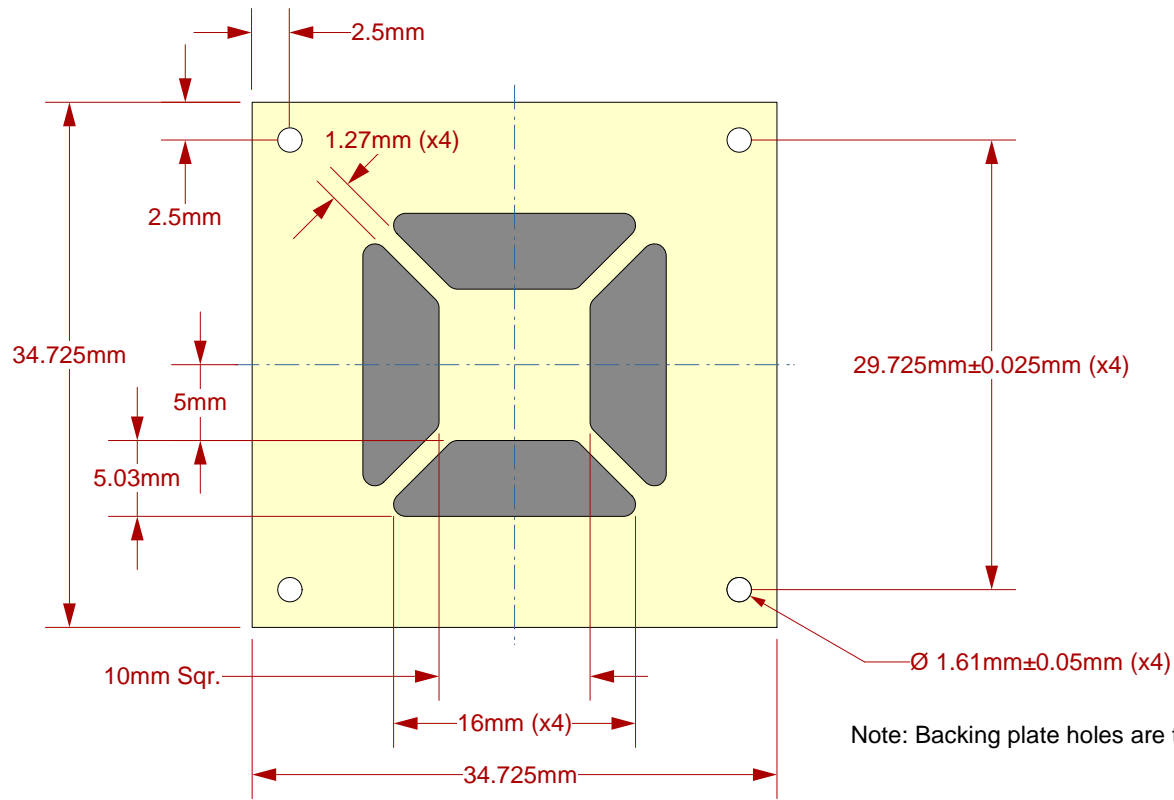
Drawing: H. Hansen

Date: 8/22/06

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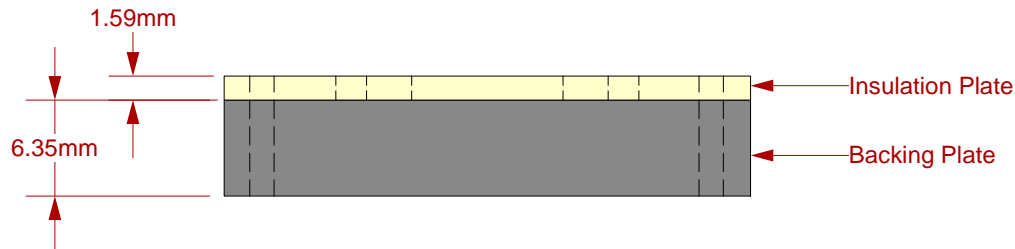
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Top View



Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Backing Plate with Insulation Plate

SG-BGA-6181 Drawing

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